

REMARKS

Claims 1-38 are currently pending. With this Response, Applicant has cancelled Claims 18-27 and 29-32. The cancellation of the claims are expressed in the detailed listing above.

Claim Rejections - 35 USC § 102

Claims 11-17, 28 stand rejected under 35 U.S.C. § 102(b) as being anticipated by Takeuchi (U.S.P.N. 4,743,841). Applicant respectfully traverses.

Claim 11 recites *inter alia*, “an integrated circuit having a test pad and a plurality of bond pads, each bond pad associated with a respective portion of the functional circuitry and for bonding out the respective portions of the functional circuitry” and “conveying a signal between the probe needle and at least one respective portion of the functional circuitry via the test pad, thus allowing the respective portions of functional circuitry to be tested using the test pad and without any contact of the plurality of bond pads by the probe needle.” Takeuchi does not disclose, teach, or suggest such limitations.

The Examiner states, “As to claim 11, Takeuchi discloses in Figs. 1-4, an integrated circuit comprising a test pad (32, 33 of figures 1) and plurality of bond pads (31 of figure 1) wherein the bond pad associated with a respective portion of the function circuitry (8, 9 of figure 1); wherein the test pad contacting with a probe needle (col. 4, lines 52-55); and a signal transmitting from the probe to at least one respective portions of functional circuitry to be tested; wherein the bond pad without any contacting with the test probe.” Applicant respectfully disagrees.

The items designated by reference numbers 31, 32, and 33 in Takeuchi are all bonding pads on an integrated circuit (IC) chip. These bonding pads are used for both normal operation and testing of the IC chip. Takeuchi expressly states, “In the above embodiment, no additional bonding pads are provided and the normal bonding pads 31 to 33

are commonly used for the normal operation mode and the test mode.” Col. 4, lines 58-61. Each of these bonding pads 31, 32, and 33 in Takeuchi would be contacted by a probe needle during testing. Therefore, Takeuchi does not disclose or teach “conveying a signal between the probe needle and at least one respective portion of the functional circuitry via the test pad, thus allowing the respective portions of functional circuitry to be tested using the test pad and without any contact of the plurality of bond pads by the probe needle,” as recited in Claim 11. As such, Takeuchi does not anticipate Claim 11.

For at least the reasons discussed above, Applicant respectfully request that the rejection of Claim 11 under 35 U.S.C. § 102(b) be withdrawn and this claim be allowed. Furthermore, because each of Claims 12-17 depend from Claim 11 and include further limitations, Applicant respectfully requests that the rejection of these dependent claims under 35 U.S.C. § 102(b) also be withdrawn and these dependent claims be allowed.

Claim 28 recites *inter alia*, “means for bonding wires to the functional circuitry; means for applying one or more test signals to the functional circuitry, such that the means for bonding are not contacted by probe pins when the integrated circuit die is tested.” Takeuchi does not disclose or teach such limitations.

The Examiner states, “As to claim 28, Takeuchi discloses in Figs. 1-4, an integrated circuit and method for testing function circuitry of an integrated circuit comprising: functional circuits (8, 9 of figure 1); means (30-33 of figure 1) for bonding wires to the functional circuitry (8, 9 of figure 1); means (Vcc) for applying one or more test signals to the functional circuitry (8, 9 of figure 1), wherein the bond pad (31 of figure 1) are not contacted by probe pins.” Applicant respectfully disagrees.

As discussed above, the items designated by reference numbers 31, 32, and 33 in Takeuchi are all bonding pads on an integrated circuit (IC) chip. These bonding pads are used for both normal operation and testing of the IC chip, and thus would be contacted by a probe needle during testing. Therefore, Takeuchi does not disclose or teach “means for applying one or more test signals to the functional circuitry, such that the means for bonding

are not contacted by probe pins when the integrated circuit die is tested,” as recited in Claim 28. As such, Takeuchi does not anticipate Claim 28.

For at least the reasons discussed above, Applicant respectfully request that the rejection of Claim 28 under 35 U.S.C. § 102(b) be withdrawn and this claim be allowed.

Allowable Subject Matter

Applicant appreciates the Examiner’s allowance of Claims 1-10 and 33-38.

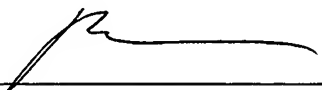
CONCLUSION

Applicant respectfully requests that the pending claims be allowed and the case passed to issue. Should the Examiner wish to discuss the Application, it is requested that the Examiner contact the undersigned at (415) 772-7428.

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Respectfully submitted,

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